



2017 Asia Pacific Microwave Conference

13 – 16 November 2017
Renaissance Kuala Lumpur Hotel
www.apmc2017.com

75 GHz InP DHBT Power Amplifier Based on Two-Stacked Transistors

Michele Squartecchia[#], Virginio Midili[#], Tom K. Johansen[#],
Jean-Yves Dupuy^{*}, Virginie Nodjiadjim^{*}, Muriel Riet^{*}, Agnieszka Konczykowska^{*}

[#] Department of Electrical Engineering, Technical University of Denmark

^{*} III-V Lab (joint lab of Nokia Bell Labs, Thales, and CEA-Leti), France



Microwaves for the
Internet of Things

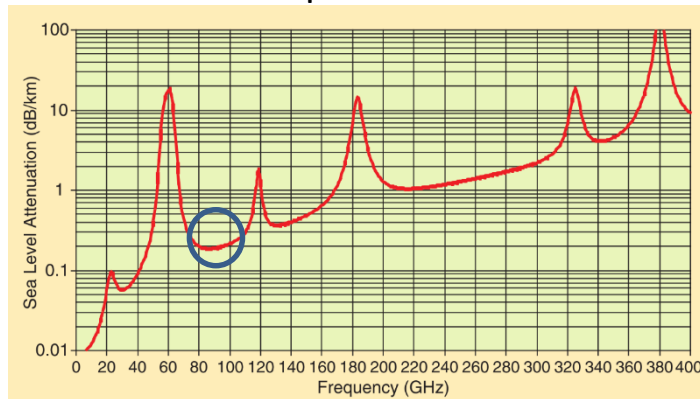
Outline

- Introduction and motivation
- Stacked-transistor configuration
- InP technology at III-V Lab
- Two-stacked transistor power cell
- Two-stage 8-way power amplifier
- Ongoing and future works
- Conclusions

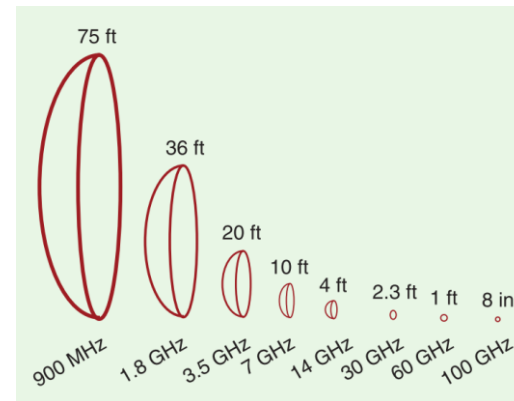
Introduction and motivation

- The W-band (75-110 GHz) has very favorable features

Low atmospheric attenuation



Small system size



- Emerging applications:

- Satellite and back-haul wireless links at E-band (71-76 GHz and 81-86 GHz)
- Automotive radars (77 GHz)
- Radio astronomy and earth observation (94 GHz)
-

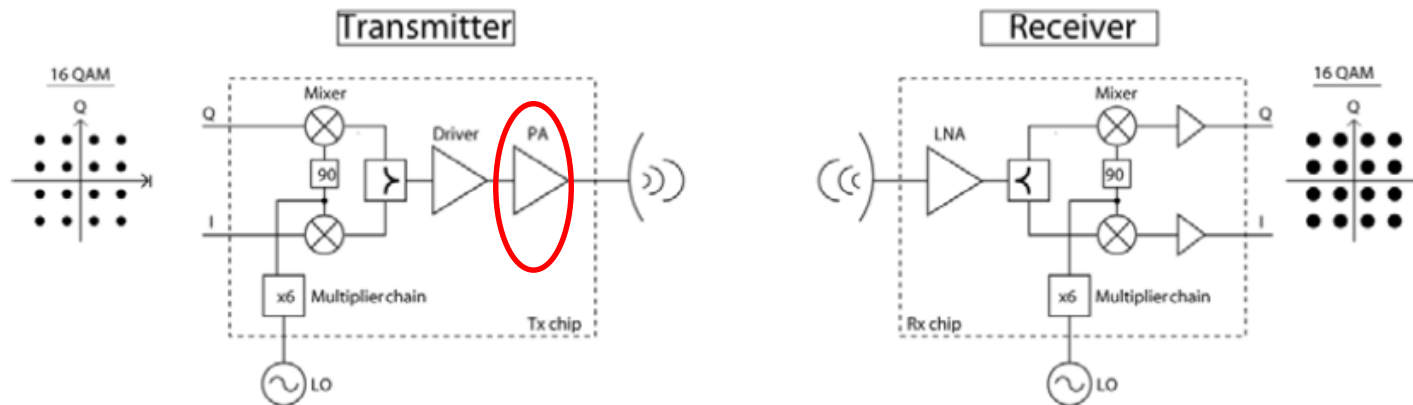
Microwaves for the
Internet of Things

NEED FOR POWER AMPLIFIERS

Introduction and motivation

- W-band power amplifiers design challenges

Ex: Wireless data link



1) High output power; 2) High gain; 3) Efficiency; 4) Good linearity

- High frequencies of operation \rightarrow device downscaling \rightarrow low breakdown voltages

$$\Rightarrow P_{Tx} \cdot f^2 \approx const$$

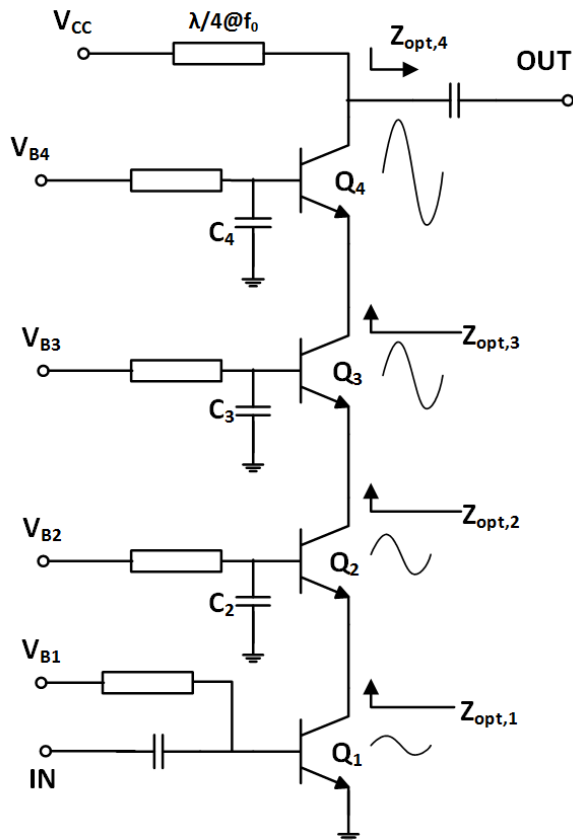
- Investigation on topologies to overcome these limitations

Outline

- Introduction and motivation
- **Stacked-transistor configuration**
- InP technology at III-V Lab
- Two-stacked transistor power cell
- Two-stage 8-way power amplifier
- Ongoing and future works
- Conclusions

Microwaves for the
Internet of Things

Stacked-transistor configuration



- The overall output voltage swing is n times higher than a single device
- Approximately the same current flows through all the transistors



- Output power and gain are potentially n times higher than a single device
- Design constraints:
 - Voltage equally shared
 - Phase alignment
 - Interstage matching

Outline

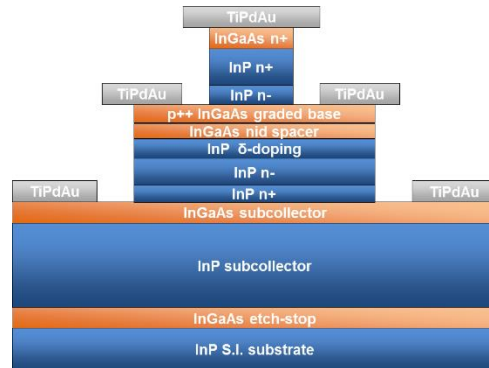
- Introduction and motivation
- Stacked-transistor configuration
- **InP technology at III-V Lab**
- Two-stacked transistor power cell
- Two-stage 8-way power amplifier
- Ongoing and future works
- Conclusions



Microwaves for the
Internet of Things

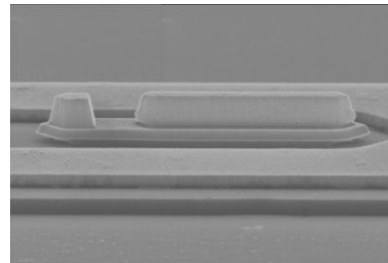
InP technology at III-V Lab

Double Heterojunction Bipolar Transistors (DHBTs)

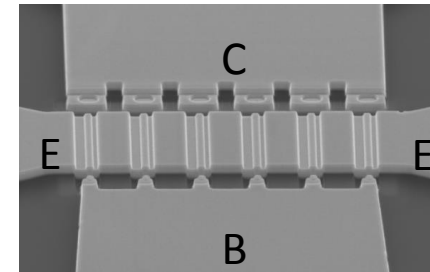


Emitter width: $W_E = 0.7 \mu\text{m}$

Single-finger device



Multifinger device



Available emitter lengths: $L_E = 5 \mu\text{m}, 7 \mu\text{m}$ and $10 \mu\text{m}$

High-speed mixed-signal optimized process (aka SHARC)

- $\beta > 25$
- $f_T \approx 400 \text{ GHz}$
- $f_{\text{max}} > 350 \text{ GHz}$
- $BV_{\text{ceo}} \approx 5 \text{ V}$











Power optimized process (aka SAND)

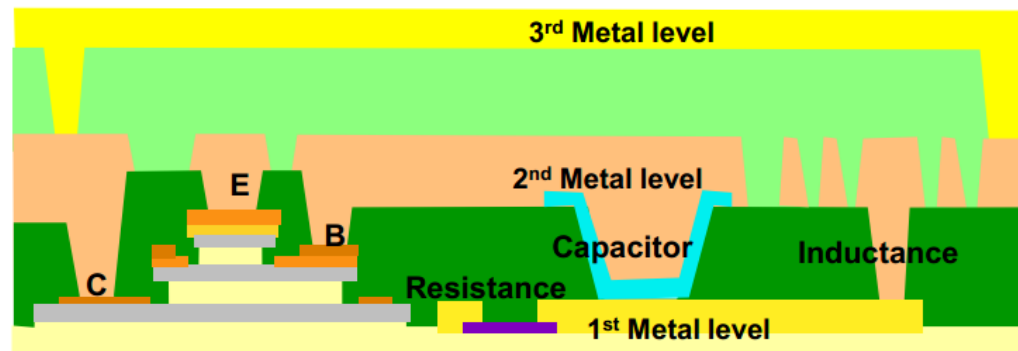
- Thicker collector
- $\beta > 25$
- $f_T \approx 270 \text{ GHz}$
- $f_{\text{max}} > 420 \text{ GHz}$
- $BV_{\text{ceo}} \approx 7 \text{ V}$

Microwaves for the
Internet of Things

InP technology at III-V Lab

Layer stack

	TiPdAu
	Ti/Pd/Au
	TiPdAu
	Polyimide
	Polyimide
	TiPdAu
	TiPdAu
	SiN
	NiCr
	GalnAs



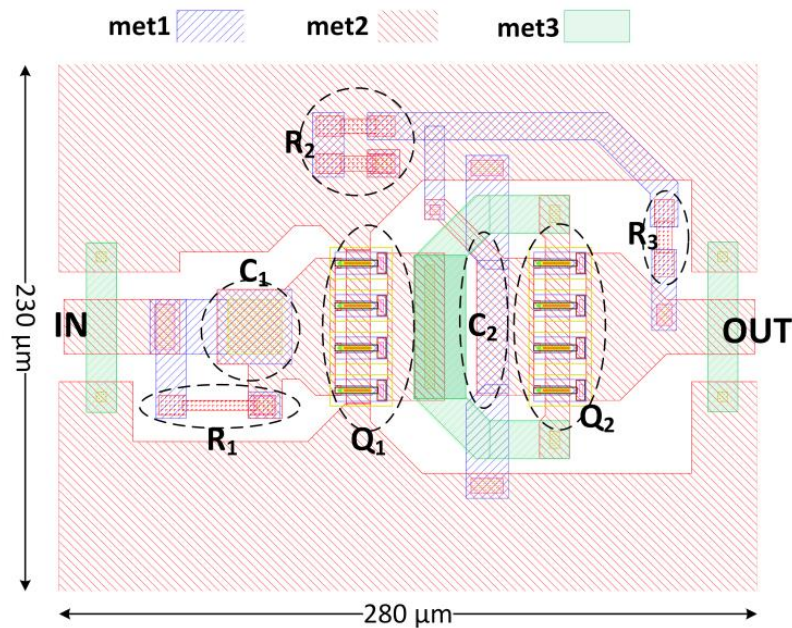
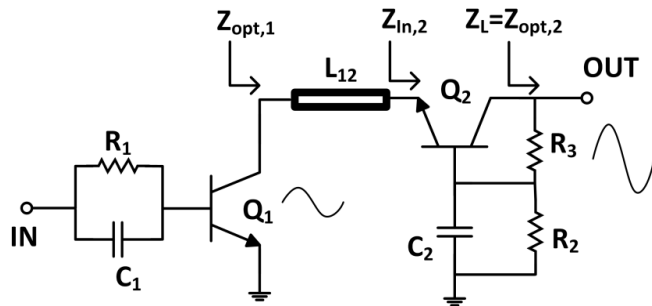
Microwaves for the
Internet of Things

Outline

- Introduction and motivation
- Stacked-transistor configuration
- InP technology at III-V Lab
- **Two-stacked transistor power cell**
- Two-stage 8-way power amplifier
- Ongoing and future works
- Conclusions

Microwaves for the
Internet of Things

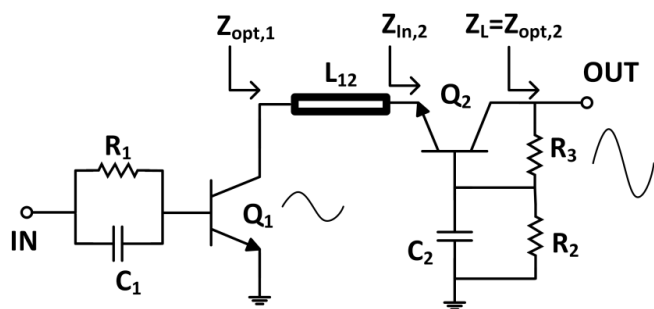
Two-stacked transistor power cell



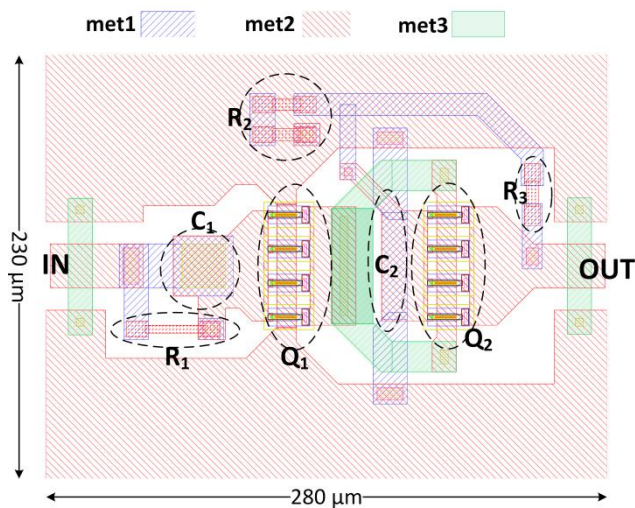
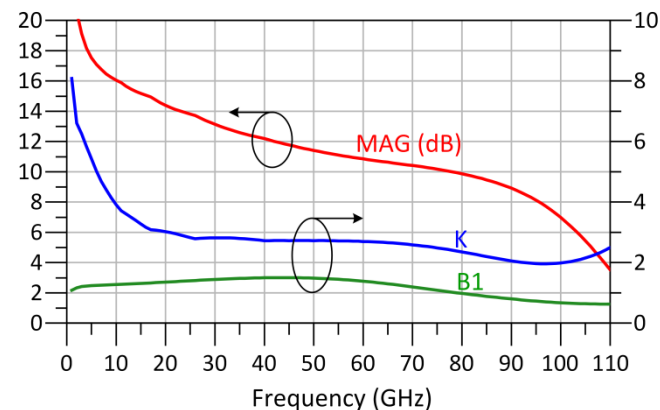
- Four-finger devices ($4 \times 0,7 \times 10 \mu\text{m}^2$)
- Q1-Q2 \rightarrow UCSD model
- Class A: $V_{ce1} = V_{ce2} = 2.4 \text{ V}$ and $I_{c1} \approx I_{c2} = 60 \text{ mA}$
- R_1 - C_1 for biasing and low frequency stability
- R_2 - R_3 for self-bias and improved stability
- L_{12} : physical connection and interstage matching

Two-stacked transistor power cell

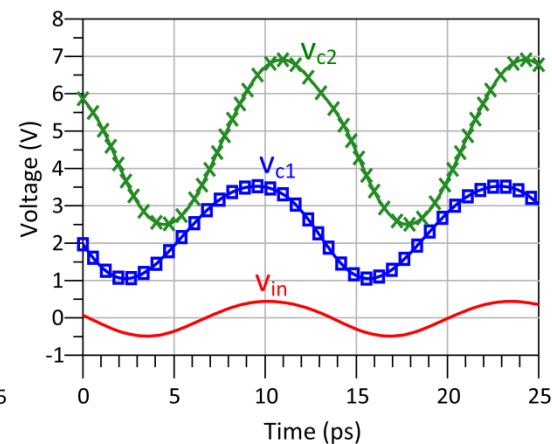
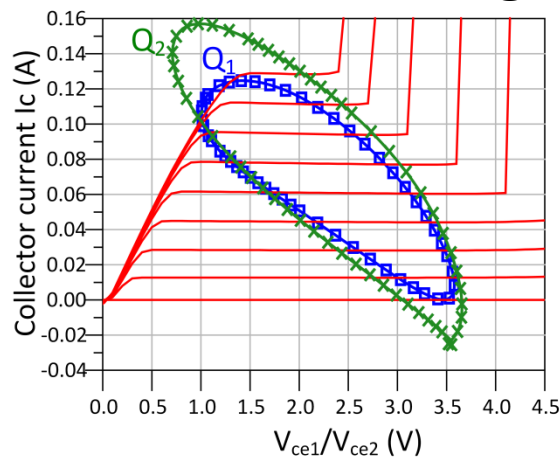
EM-circuit co-simulation and optimization



$R_1=250 \Omega$
 $C_1=300 \text{ fF}$
 $C_2=80 \text{ fF}$
 $R_2=130 \Omega$
 $R_3=60 \Omega$



@ 75 GHz



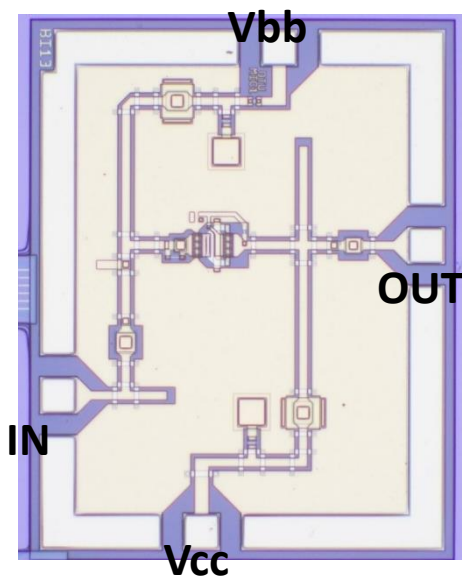
$Z_L=Z_{opt,2} \approx 14+j*8 \Omega$

$P_{in} \approx 10 \text{ dBm}$

$P_{out} \approx 18 \text{ dBm}$

Two-stacked transistor power cell

Matched power cell (SHARC process realization)

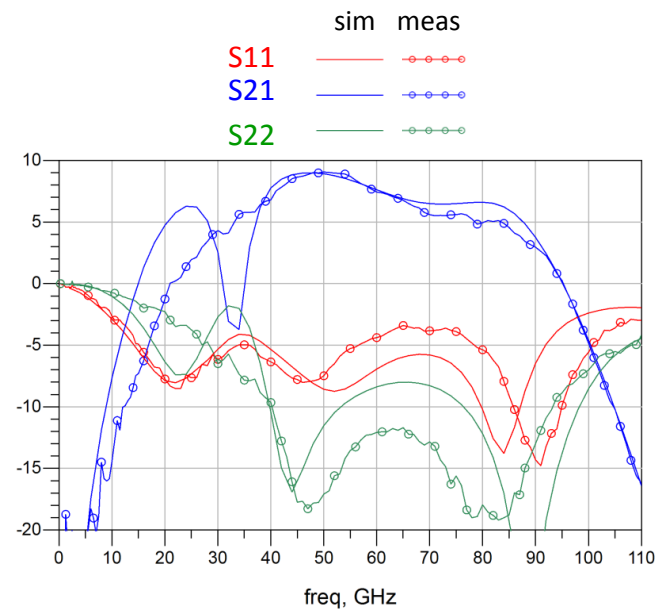
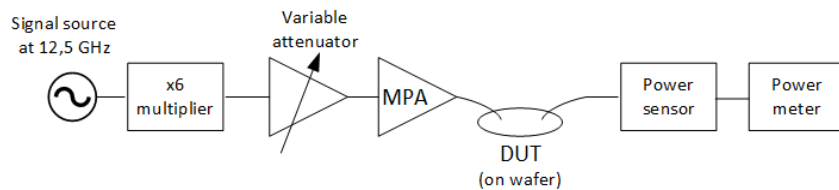


Bias settings

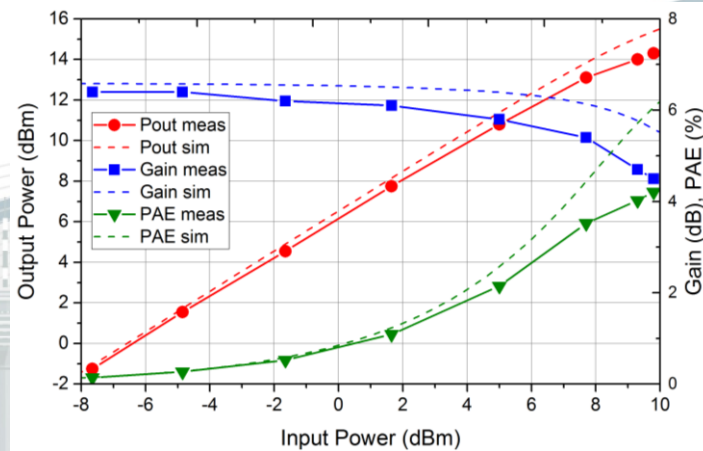
$V_{bb}=1.4\text{ V}$
 $I_{bb}=1.9\text{ mA}$

$V_{cc}=4.9\text{ V}$
 $I_{cc}=84\text{ mA}$

Power sweep measurement setup



81 GHz

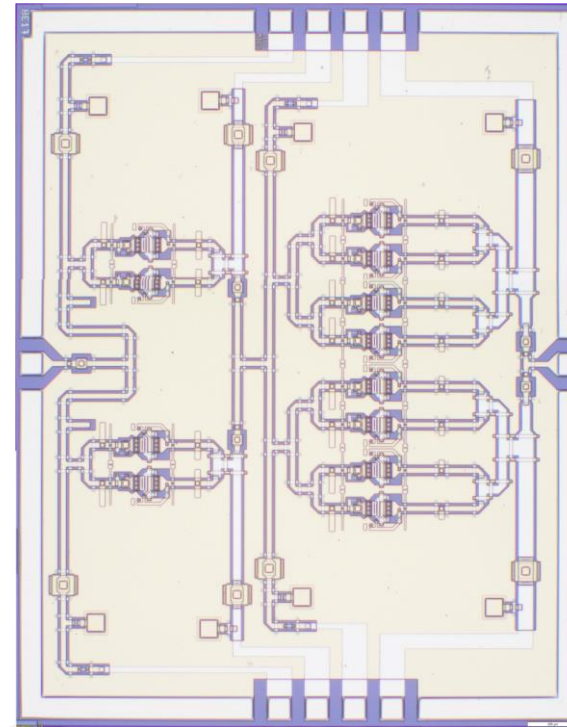
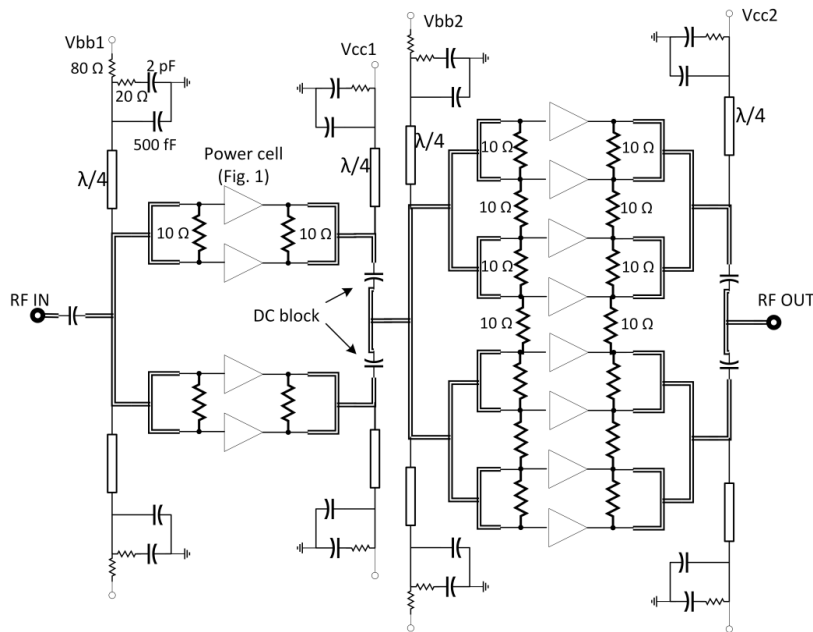


Outline

- Introduction and motivation
- Stacked-transistor configuration
- InP technology at III-V Lab
- Two-stacked transistor power cell
- **Two-stage 8-way power amplifier**
- Ongoing and future works
- Conclusions

Microwaves for the
Internet of Things

Two-stage 8-way power amplifier



Bias settings

$V_{bb1}=1.7\text{ V}$
 $I_{bb1}=4,1\text{ mA}$

$V_{cc1}=4\text{ V}$
 $I_{cc1}=172\text{ mA}$

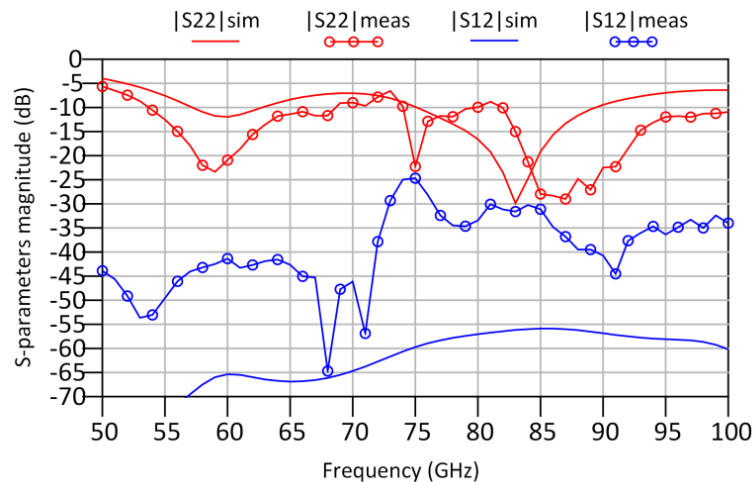
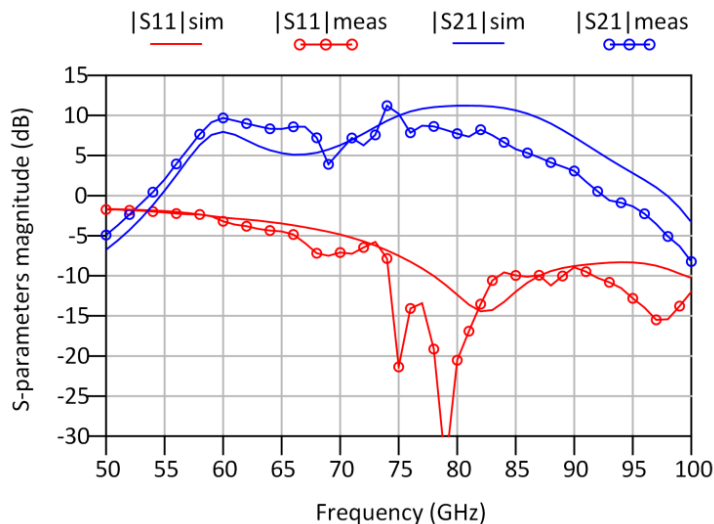
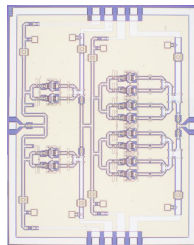
$V_{bb1}=2\text{ V}$
 $I_{bb1}=8\text{ mA}$

$V_{cc2}=4,5\text{ V}$
 $I_{cc2}=340\text{ mA}$

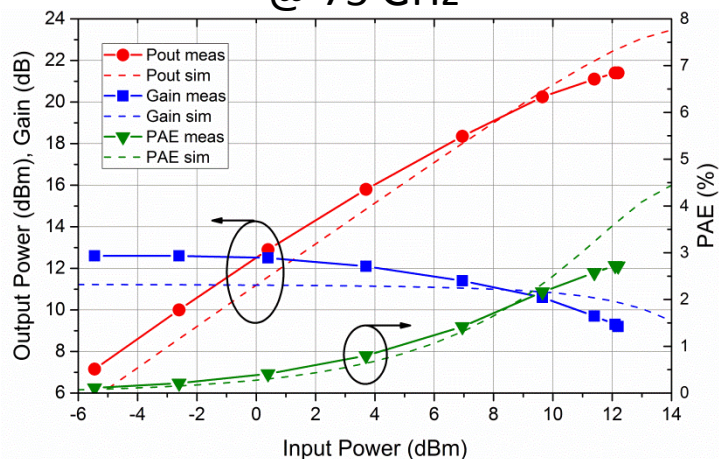
$2.4 \times 3\text{ mm}^2$

Microwaves for the
Internet of Things

Two-stage 8-way power amplifier



@ 75 GHz



- Gain \approx 12 dB

- $P_{out,1dB} \approx$ 18 dBm

- $P_{sat} >$ 21 dBm

Microwaves for the
Internet of Things

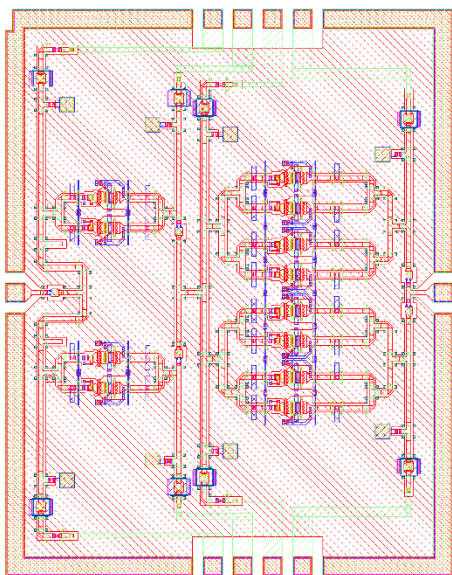
Outline

- Introduction and motivation
- Stacked-transistor configuration
- InP technology at III-V Lab
- Two-stacked transistor power cell
- Two-stage 8-way power amplifier
- **Ongoing and future works**
- Summary and conclusions

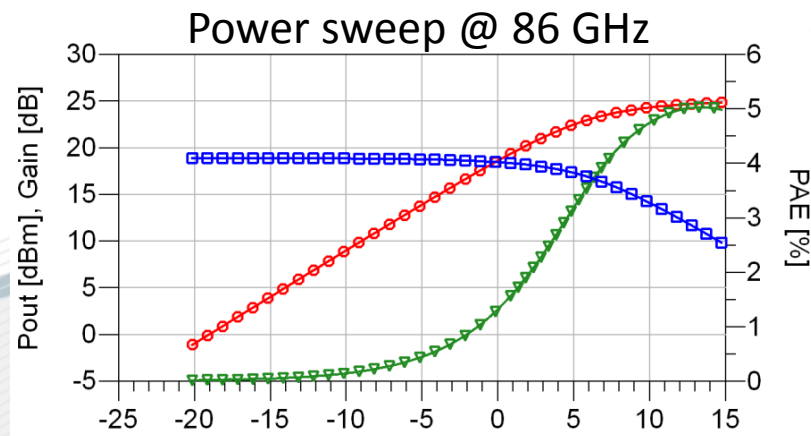
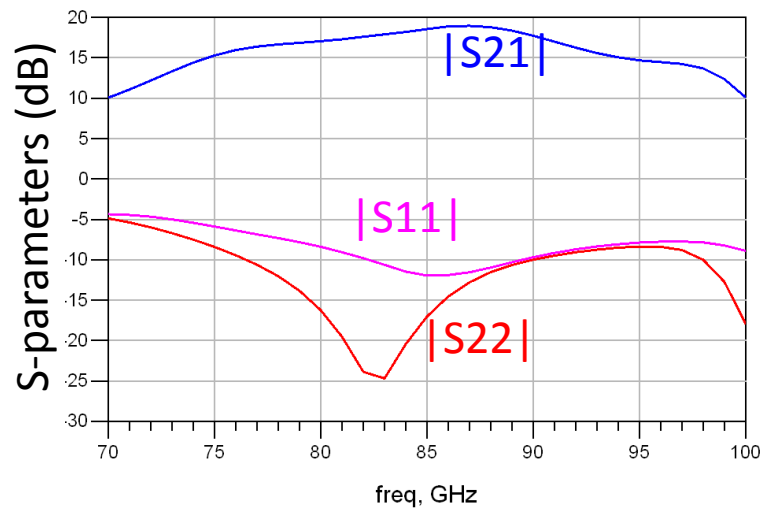
Microwaves for the
Internet of Things

Ongoing and future works

Simulation results on power optimized
process SAND

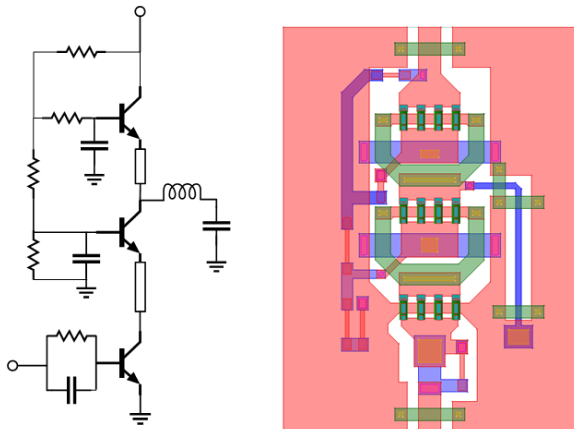


- Gain ≈ 18 dB
- $P_{\text{out},1\text{dB}} \approx 22$ dBm
- $P_{\text{sat}} > 24$ dBm

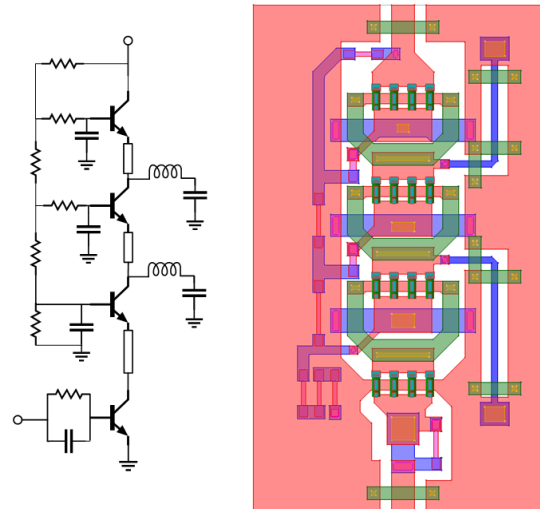


Ongoing and future works

Three-stacked transistor

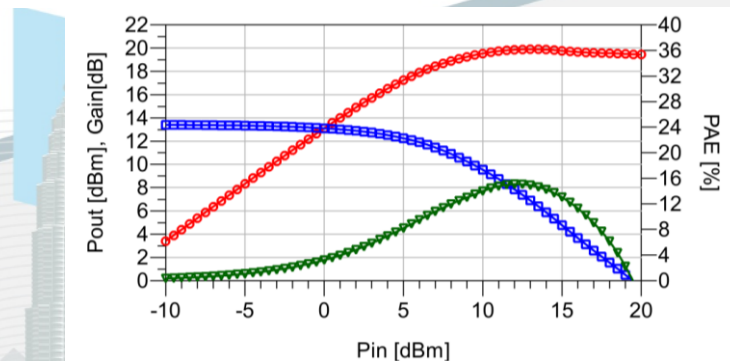
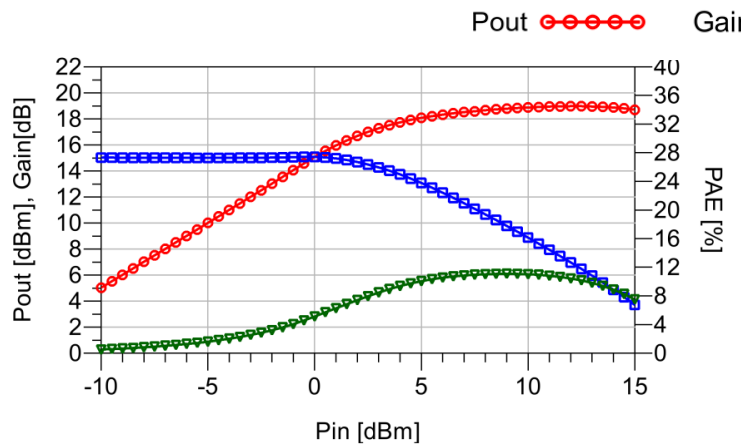


Four-stacked transistor



Preliminary results (SAND process)

Simulated power sweep at 86 GHz



Outline

- Introduction and motivation
- Stacked-transistor configuration
- InP technology at III-V Lab
- Two-stacked transistor power cell
- Two-stage 8-way power amplifier
- Ongoing and future works
- **Summary and conclusions**

Microwaves for the
Internet of Things

Summary and conclusions

- This work represents an attempt to extend the stacked-transistor concept to InP DHBT technology in order to get higher performances in terms of output power, gain and efficiency.
- A two-stage eight-way 75 GHz power amplifier based on two-stacked transistors has been designed and tested.
 $G \approx 12$ dB, $P_{\text{out},1\text{dB}} \approx 18$ dBm and $P_{\text{sat}} > 21$ dBm have been obtained experimentally.
- Better performances are expected from a power optimized process currently under development.
- Three- and four-stacked power cells under investigation with promising preliminary results.

Acknowledgments



IN-POWER



**InP DHBT MMIC Technology for Millimeter-Wave
Power Applications**

Microwaves for the
Internet of Things



2017 Asia Pacific
Microwave Conference

13 - 16 November 2017
Renaissance Kuala Lumpur Hotel

Acknowledgments

Thank you for your attention!

Microwaves for the
Internet of Things